Specification for Approval

Customer:_____

Model Name:_____

Supplier Approval			Customer approval
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		

Revision Record

REV NO.	REV DATE	CONTENTS	Note
A	2017-04-10	NEW ISSUE	

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1. Scope

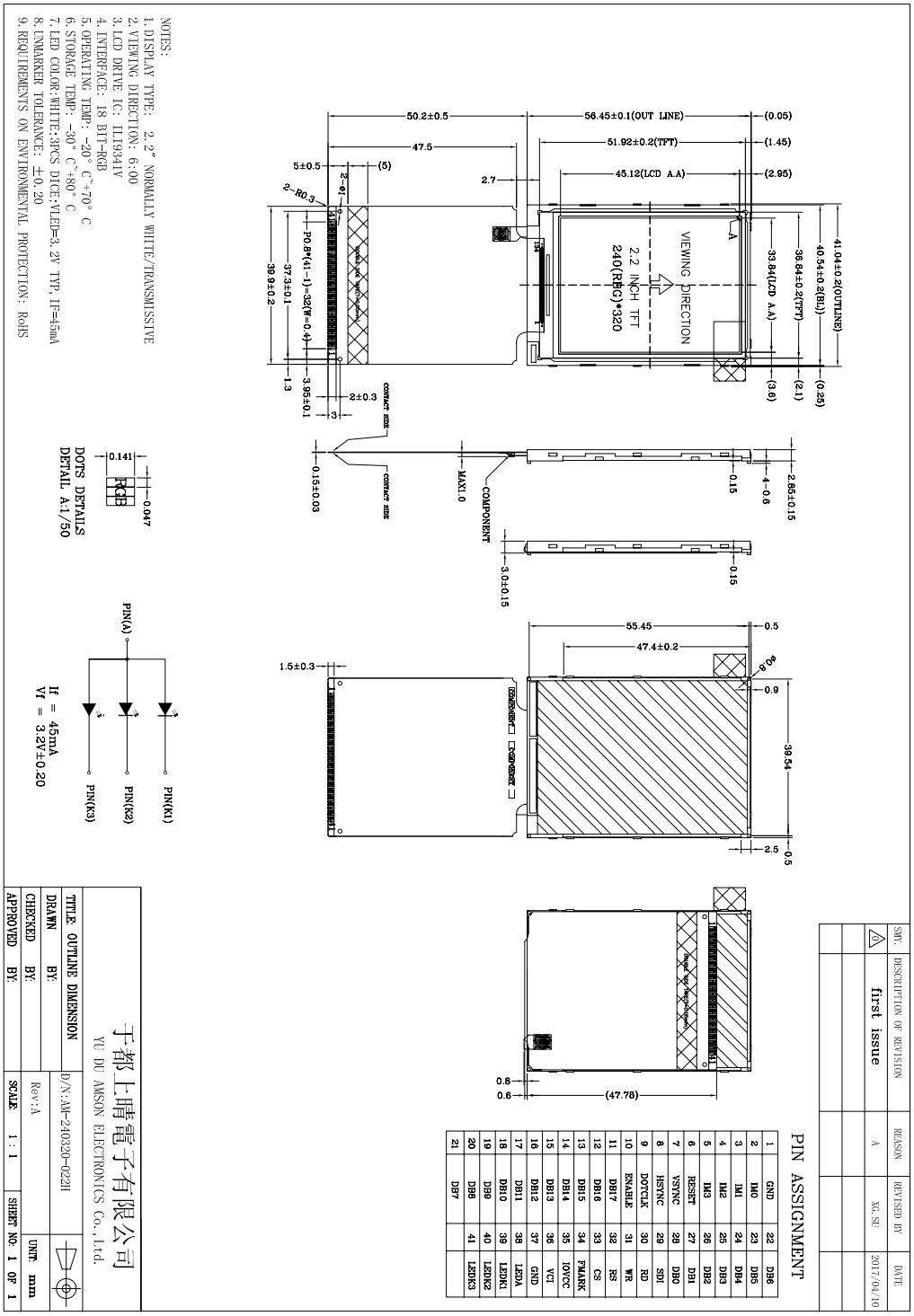
This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	2.2”TFT	--
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	--
Display mode	TFT / Transmission / Normally White	--
Viewing Direction	12 O’clock (Gray inversion)	--
Driver IC	ILI9341V	--
Module size	41.04(W)×56.45(H)×2.85(T)	mm
Active area	33.84(W)×45.12(H)	mm
Dot pitch	0.141(W)×0.141(H)	mm
Interface	18-BIT RGB/MCU	--
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	3 White LED	--
Weight	TBD	g

3. External Dimensions



4. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1	GND	Ground
2~5	IM0~IM3	Select the MCU interface mode. Fix this pin at IOVCC or GND. *Note
6	RESET	This signal will reset the device and must be applied to properly initialize the chip. Signal is active low.
7	VSYNC	Frame synchronizing signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
8	HSYNC	Line synchronizing signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
9	DOTCLK	Dot clock signal for RGB interface operation Fix to IOVCC or GND level when not in use.
10	ENABLE	Data enable signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
11~28	DB17~DB0	Data bus
29	SDI	When IM[3]: Low, Serial in/out signal. When IM[3]: High, Serial in/out signal. The data is applied on the rising edge of the SCL signal. If not used,fix this pin at IOVCC or GND.
30	RD	8080-/808 I 0-II system(RDX):Serves as a read signal and MCU read data at the rising edge. Fix to IOVCC level when not in use.
31	WR	(WRX)-8080-I/8080-II system:Serves as a write signal and writes data at the rising edge. (D/CX)-4 line system:Serves as the selector of command or parameter. Fix to IOVCC level when not in use.
32	RS	(D/CX)-This pin is used to select “Data or Command” in the parallel interface. When DCX=1,data is selected. When DCX=0,command is selected. (SCL): This pin is used as the serial interface clock in 3-wire 9-bit/4-wire 8-bit serial data interface. If not used,this pin should be connected to IOVCC or GND.
33	CS	Chip select input pin(“LOW”enable). This pin can be permanently fixed “Low” in MPU interface mode only.
34	FMARK	Tearing effect output pin to synchronize MPU to frame writing,activated by S/W command. When this pin is not activated,this pin is low. If not used, open this pin.
35	IOVCC	Power supply for logic.
36	VCI	Power supply for analog.
37	GND	Power ground

38	LEDA	Anode of LED backlight
39~41	LEDK1-K3	Cathode of LED backlight

Note: Select the MCU interface mode.
MPU Parallel interface bus and serial interface select
If use RGB Interface must select serial interface.

IM3	IM2	IM1	IM0	MCU-Interface Mode	DB Pin in use	
					Register/Content	GRAM
0	0	0	0	80 MCU 8-bit bus interface Ⅰ	D[7:0]	D[7:0]
0	0	0	1	80 MCU 16-bit bus interface Ⅰ	D[7:0]	D[15:0]
0	0	1	0	80 MCU 9-bit bus interface Ⅰ	D[7:0]	D[8:0]
0	0	1	1	80 MCU 18-bit bus interface Ⅰ	D[7:0]	D[17:0]
0	1	0	1	3-wire 9-bit data serial interface Ⅰ	SDA: In/OUT	
0	1	1	0	4-wire 8-bit data serial interface Ⅰ	SDA: In/OUT	
1	0	0	0	80 MCU 16-bit bus interface Ⅱ	D[8:1]	D[17:10], D[8:1]
1	0	0	1	80 MCU 8-bit bus interface Ⅱ	D[17:10]	D[17:10]
1	0	1	0	80 MCU 18-bit bus interface Ⅱ	D[8:1]	D[17:0]
1	0	1	1	80 MCU 9-bit bus interface Ⅱ	D[17:10]	D[17:9]
1	1	0	1	3-wire 9-bit data serial interface Ⅱ	SDI: In SDO: Out	
1	1	1	0	4-wire 8-bit data serial interface Ⅱ	SDI: In SDO: Out	

5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCI	-0.3	4.6	V
Supply current(One LED)	ILED		30	mA
Operating Temperature	TOP	-20	70	°C
Storage Temperature	TST	-30	80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times.Should a module be used with any of the absolute maximum ratings exceeded.the characteristics of the module may not be recovered. Or in an extreme case,the module may be permanently destroyed.

6. DC Characteristics

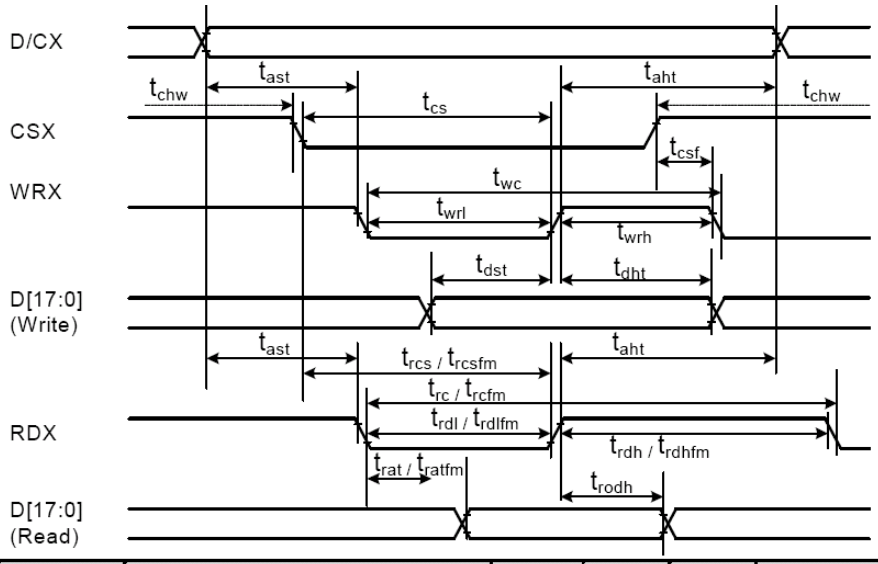
Item	Symbol	Min.	Typ.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	V	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	V	-
Input High Voltage	V_{IH}	0.8IOVCC	-	IOVCC	V	-
Input Low Voltage	V_{IL}	GND	-	0.3 VCC	V	-
I/O Leak Current	ILKG	-1	-	1	uA	-

Note:

Brightness to be decreased to 50% of the initial value at ambient temperature TA=25℃。

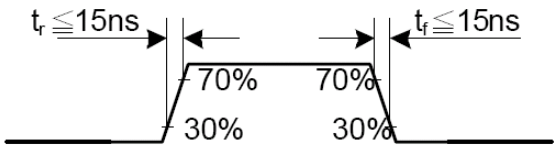
7. Timing Characteristics

7.1 Parallel 18/16/9/8-bit interface timing characteristics(80-I system)

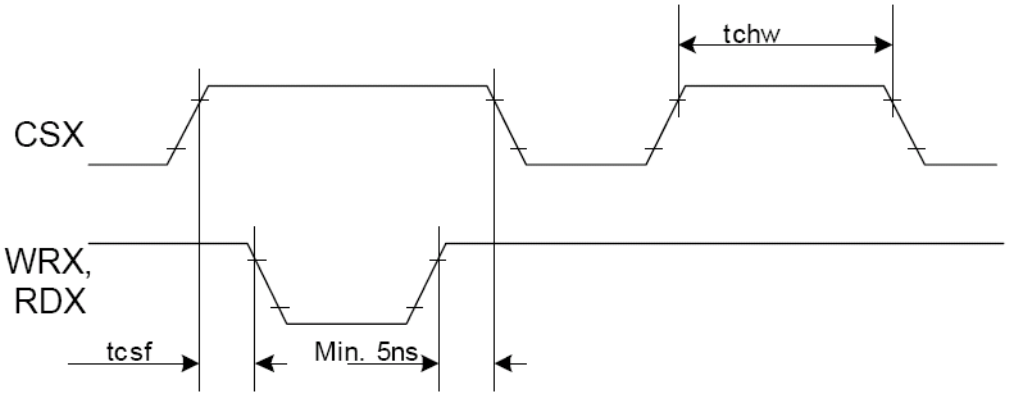


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V

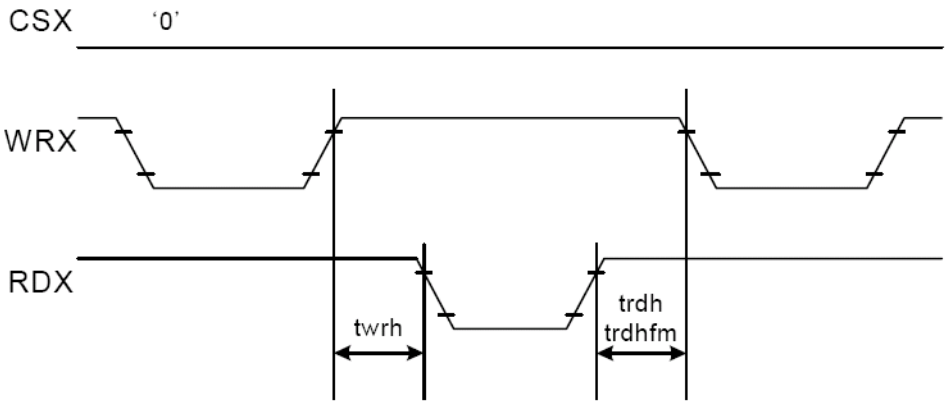


CSX timings :



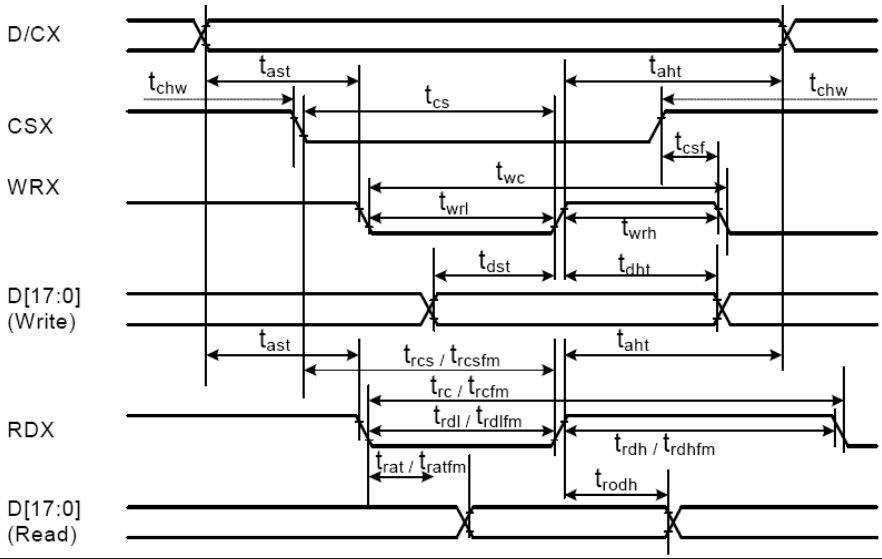
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



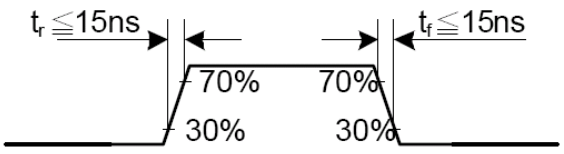
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

7.2 Parallel 18/16/9/8-bit interface timing characteristics(80-II system)

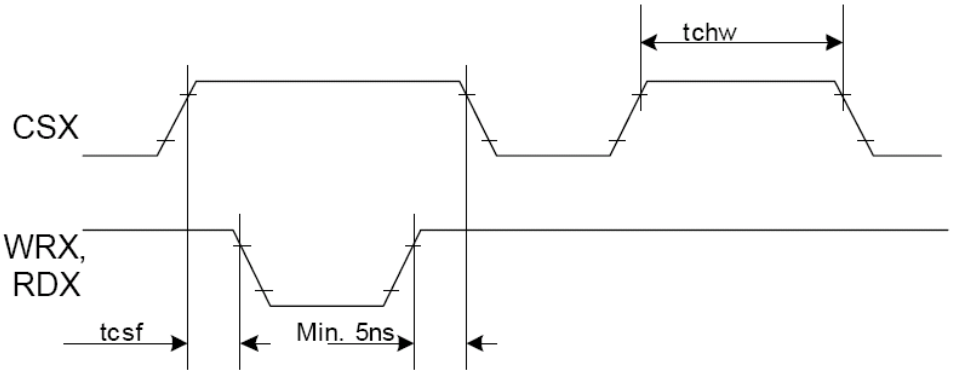


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.

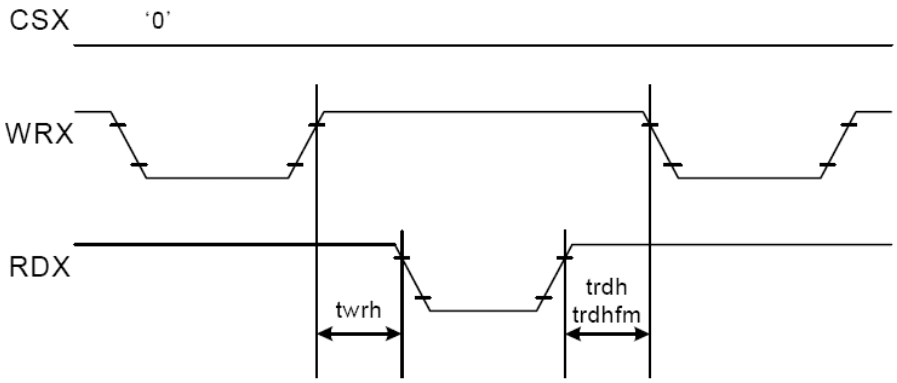


CSX timings :



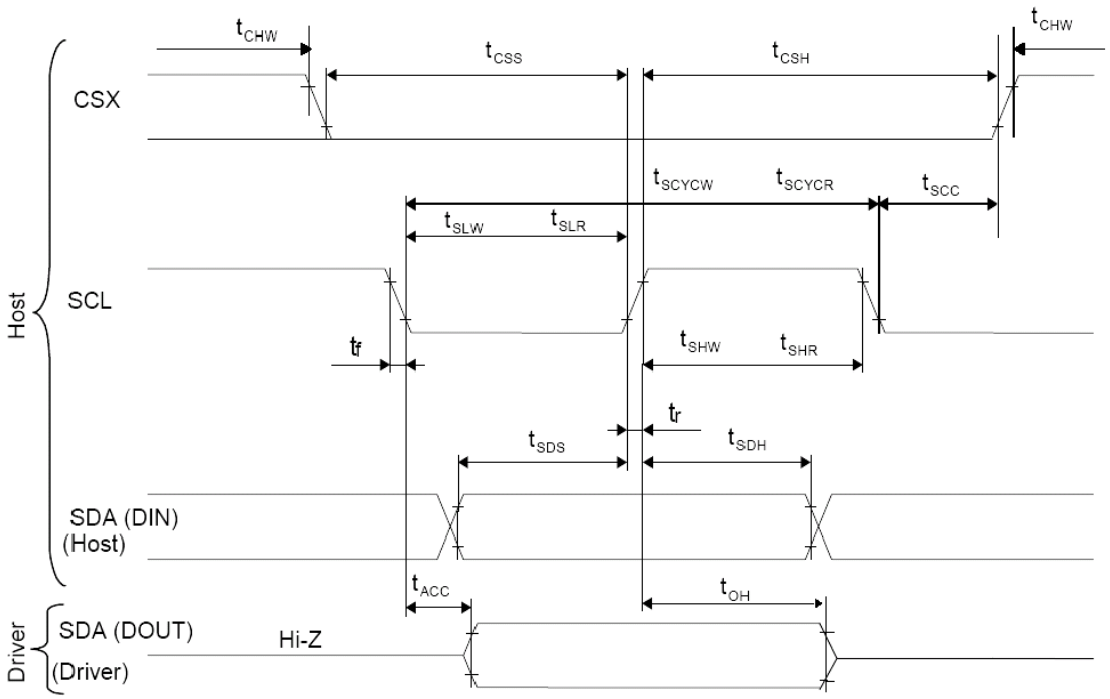
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



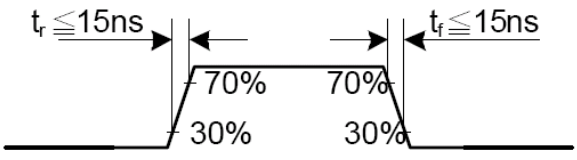
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

7.3 Serial interface timing characteristics(3-line SPI system)

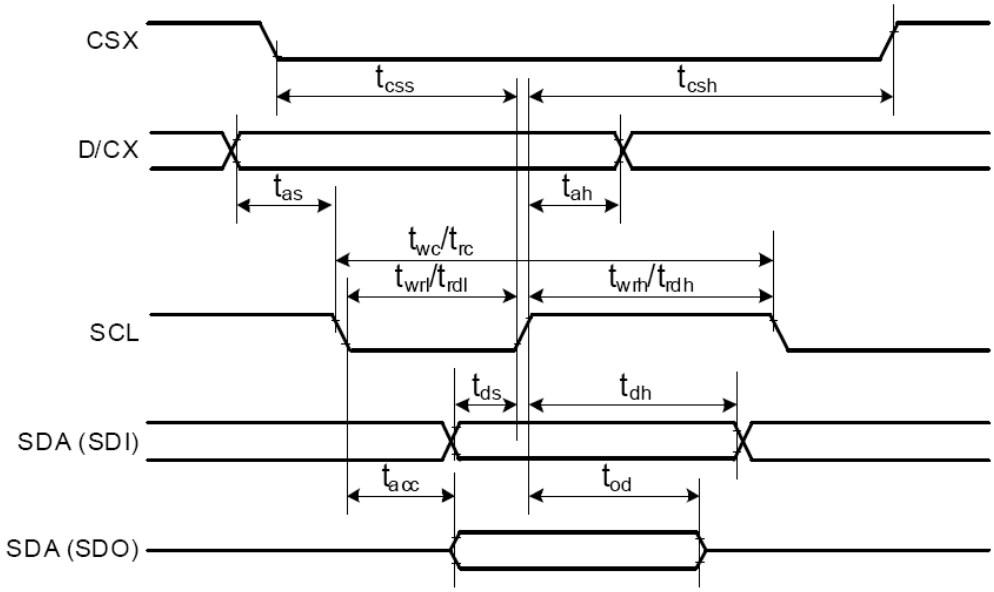


Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL “H” Pulse Width (Write)	40	-	ns	
	tslw	SCL “L” Pulse Width (Write)	40	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL “H” Pulse Width (Read)	60	-	ns	
	tslr	SCL “L” Pulse Width (Read)	60	-	ns	
SDA / SDI (Input)	tsds	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	10	50	ns	
CSX	tscc	SCL-CSX	20	-	ns	
	tchw	CSX “H” Pulse Width	40	-	ns	
	tcss	CSX-SCL Time	60	-	ns	
	tcsh		65	-	ns	

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

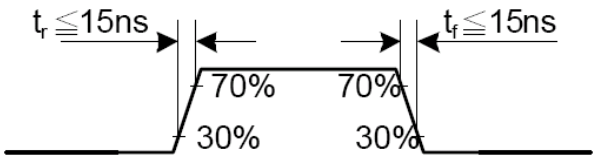


7.4 Serial interface timing characteristics(4-line SPI system)

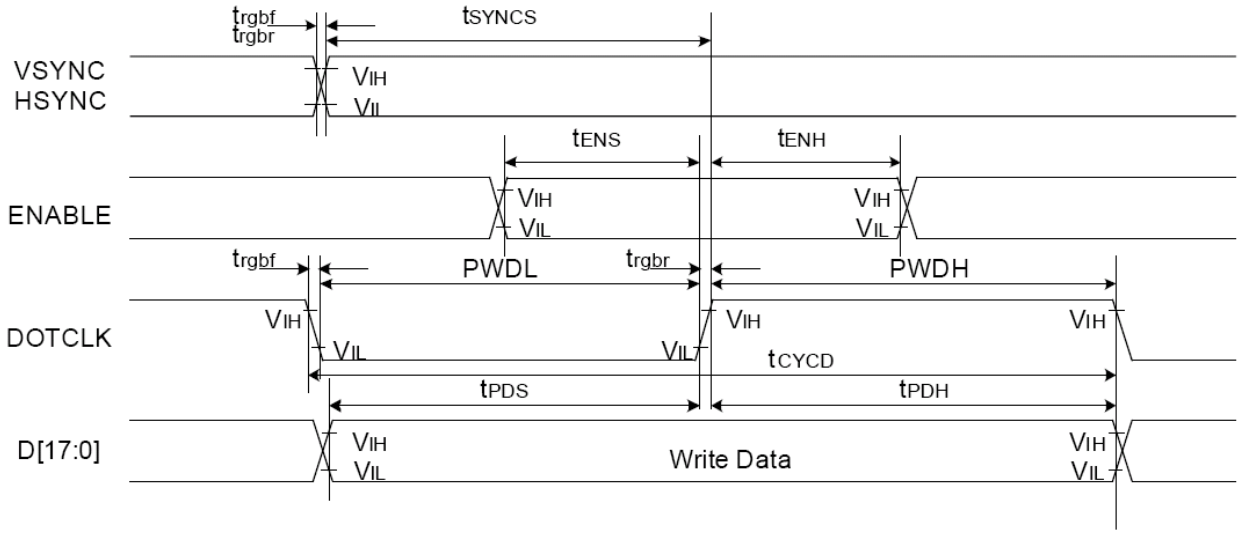


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	40	-	ns	
	tcsh	Chip select hold time (Read)	40	-	ns	
SCL	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL “H” pulse width (Write)	40	-	ns	
	twrl	SCL “L” pulse width (Write)	40	-	ns	
	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL “H” pulse width (Read)	60	-	ns	
	trdl	SCL “L” pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-		
	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI (Input)	tds	Data setup time (Write)	30	-	ns	
	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

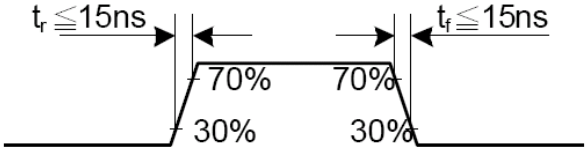


7.5 Parallel 18/16/6-bit RGB interface timing characteristics

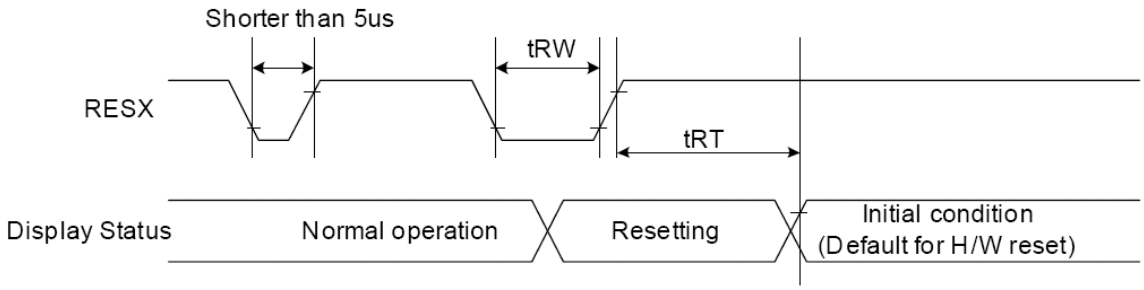


Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	15	-	ns	
	PWDL	DOTCLK low-level period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level pulse period	15	-	ns	
	PWDL	DOTCLK low-level pulse period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V



7.6 Reset timing



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

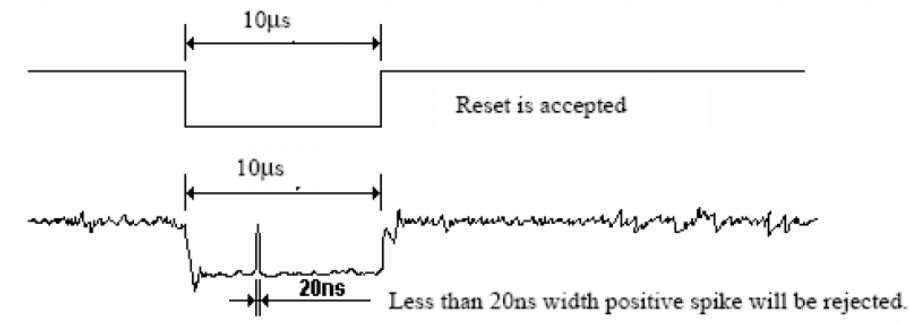
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:

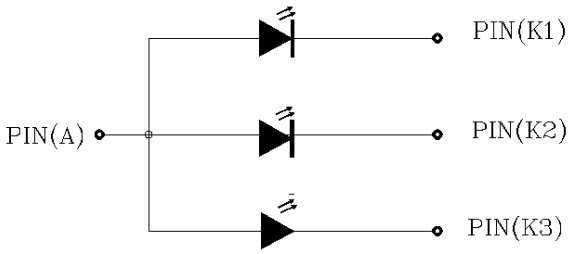


Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

8. Backlight Characteristic

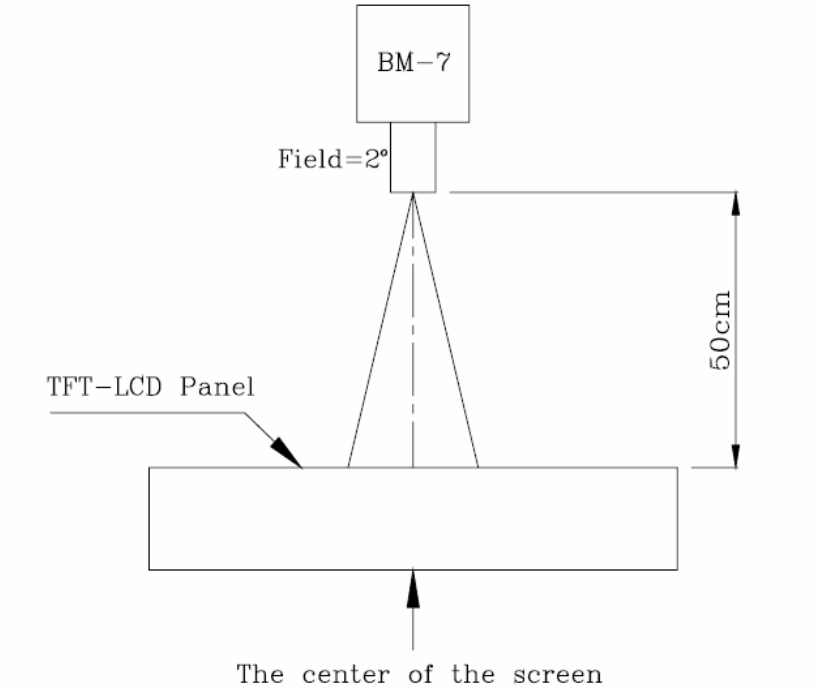


Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	-	3.2	-	V	If=45mA
Supply Current	If	-	45	-	mA	-
Luminous Intensity for LCM	-	-	200	-	Cd/m^2	If=45mA
Uniformity for LCM	-	80	-	-	%	If=45mA
Life Time	-	30000	-	-	Hr	If=45mA
Backlight Color	White					

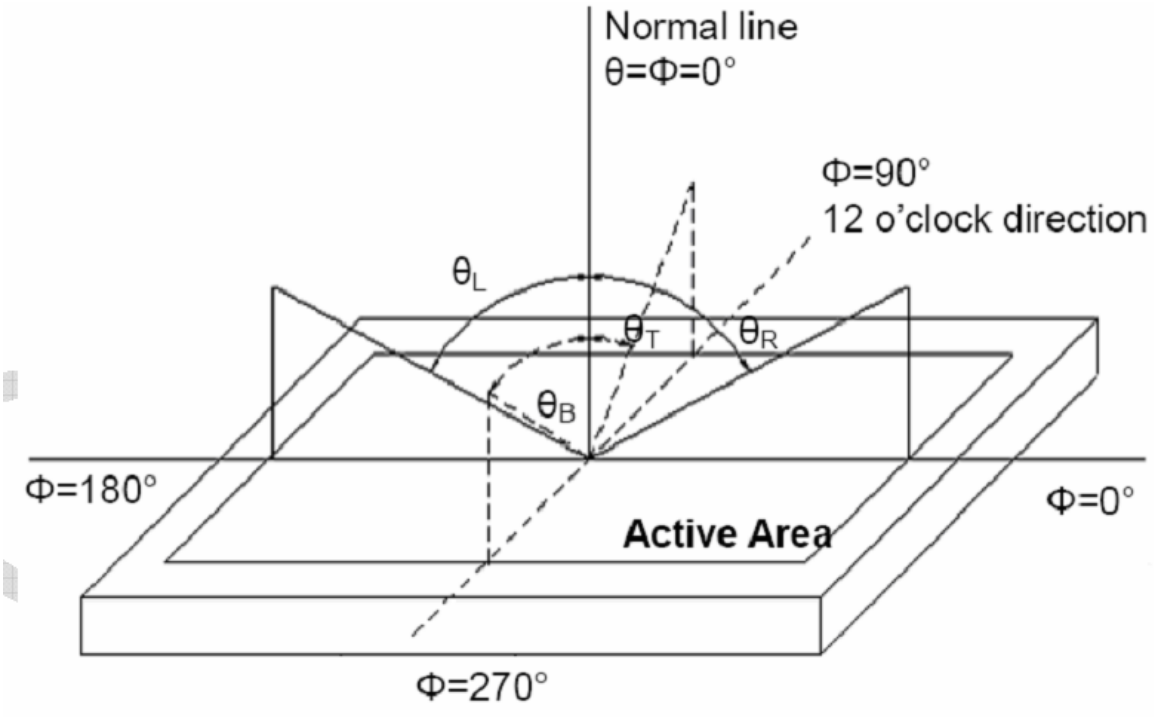
9. Optical Characteristics

Item	Conditions		Min.	Typ.	Max.	Unit	Note
Viewing Angle (CR>10)	Horizontal	θ_L	40	45	-	degree	(1),(2),(6)
		θ_R	40	45	-		
	Vertical	θ_T	45	50	-		
		θ_B	15	20	-		
Contrast Ratio	Center		250	350	-	-	(1),(3),(6)
Response Time	Rising		-	20	30	ms	(1),(4),(6)
	Falling			20	30	ms	1),(4),(6)
CF Color Chromaticity (CIE1931)	Red x			--		-	(1), (6)
	Red y			--		-	
	Green x			--		-	
	Green y			--		-	
	Blue x			--		-	
	Blue y			--		-	
	White x		0.29	0.31	0.33	-	
	White y		0.31	0.330	0.35	-	
Uniformity			80		-	%	(1),(6)

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.



Note (2) Definition of Viewing Angle



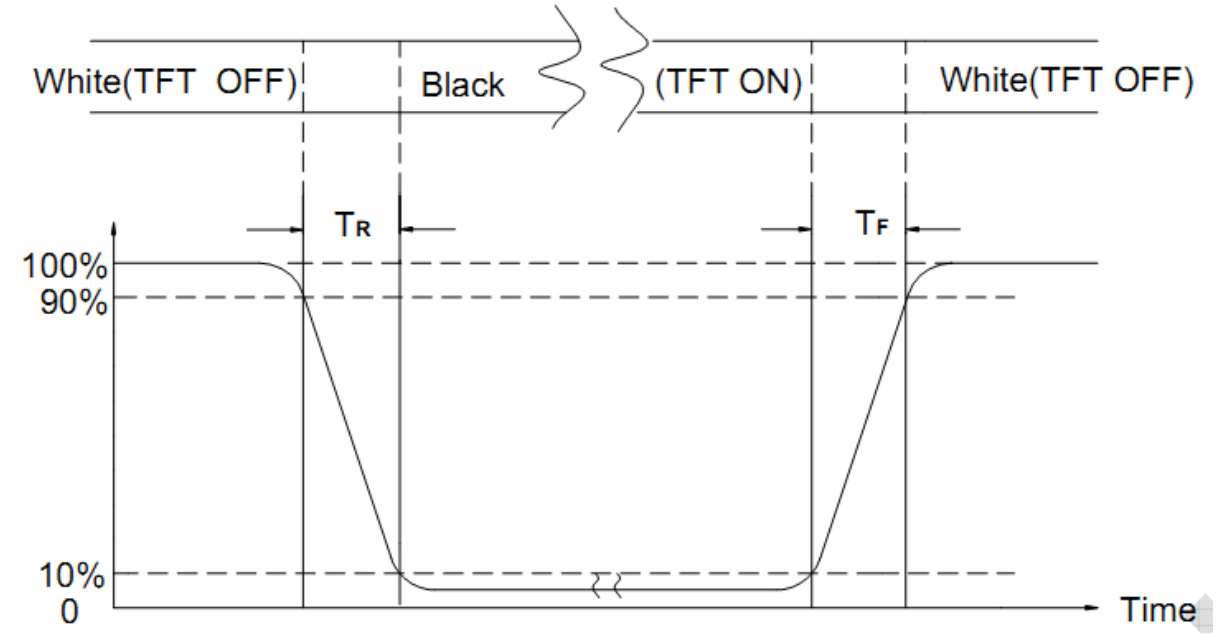
Note (3) Definition Of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression

Contrast Ratio (CR) = L63 / L0

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



Note (5) Definition of Transmittance (Module is without signal input)

Transmittance = Center Luminance of LCD / Center Luminance of Back Light x 100%

Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
①	High Temperature Storage	80°C±2°C×240Hours	Inspection after 2~4hours storage at room temperature, the samples should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack. 6, Current IDD is twice higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
②	Low Temperature Storage	-30°C±2°C×240Hours	
③	High Temperature Operating	70°C±2°C×120Hours	
④	Low Temperature Operating	-20°C±2°C×120Hours	
⑤	Temperature Cycle(Storage)	-30°C ⟺ 25°C ⟺ 80°C (30min) (5min) (30min) 1cycle Total 10cycle	
⑥	Damp Proof Test (Storage)	60°C±5°C×90%RH×240Hours	
⑦	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	
⑧	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	
⑨	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,5times	

REMARK:
1, The Test samples should be applied to only one test item.
2, Sample side for each test item is 5~10pcs.
3,For Damp Proof Test, Pure water(Resistance > 10MΩ)should be used.
4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Tecenstar.

11.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

11.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level Ⅱ take a single Time.
- The defects classify of AQL as following:
  Major defect: AQL = 0.65
  Minor defect: AQL = 2.5
  Total defects: AQL = 2.5

11.3 Non-conforming Analysis & Deal With Manners

11.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

11.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

11.4 Agreement items

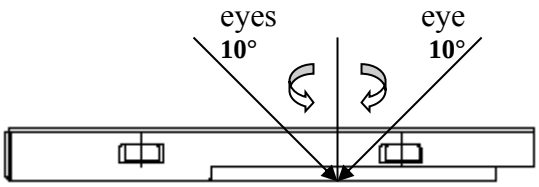
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

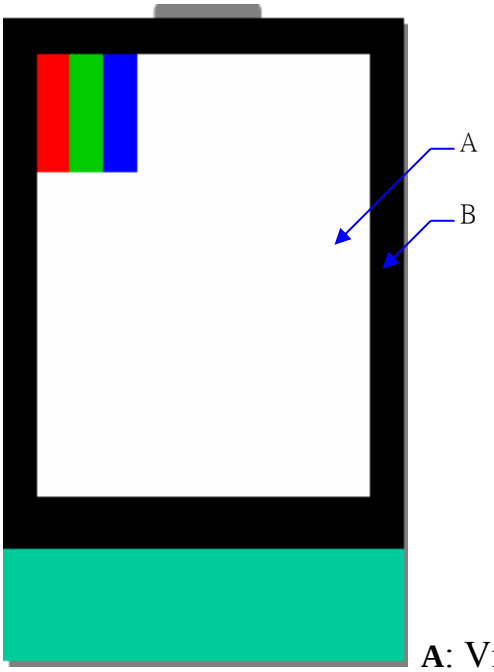
11.5 Standard of The Product Appearance Test

11.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5℃ Humidity: 60±10%RH



- Definition of area:

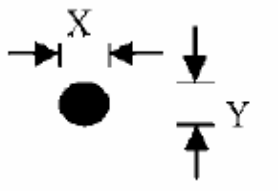


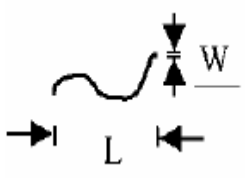
A: Viewing area B: Outside viewing area

11.5.2 Basic principle

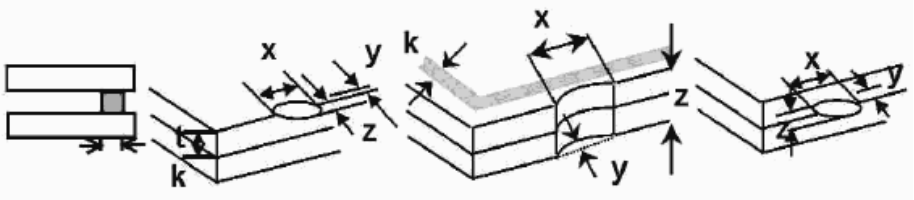
- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

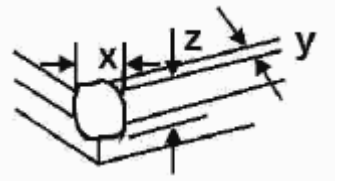
11.6 Inspection Standard

<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character, dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Flicker</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or White spots or Bright spots or Color spots on LCD (Display only)</td><td>2.1 White and black or color spots on display ≦ 0.25mm, no more than Five spots.
2.2 Densely spaced: No more than three spots within 3mm.</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD and Touch Panel black spots, white spots, contamination (non – display)</td><td>3.1 Round type: As following drawing
Φ = (X+Y) / 2
 

<table>
<tr><th>Size(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>Φ≦0.10</td><td>Accept no dense</td></tr>
<tr><td>0.10< Φ≦0.20</td><td>2</td></tr>
<tr><td>0.20< Φ≦0.25</td><td>2</td></tr>
<tr><td>0.25< Φ≦0.30</td><td>1</td></tr>
<tr><td>0.30< Φ</td><td>0</td></tr>
</table>
* Densely spaced: No more than two spots within 3mm.</td><td>2.5</td></tr>
<tr><td>3.2 Line type: (As following drawing)
 

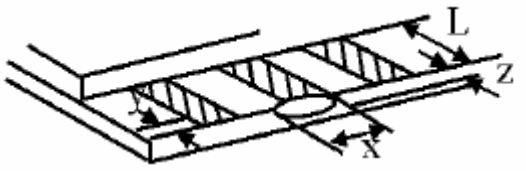
<table>
<tr><th>Length(mm)</th><th>Width(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02<W≦0.05</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03<W≦0.08</td></tr>
<tr><td>---</td><td>0.08<W</td><td>Rejection</td></tr>
</table>
* Densely spaced: No more than two lines within 3mm.</td><td>2.5</td></tr>
</table>

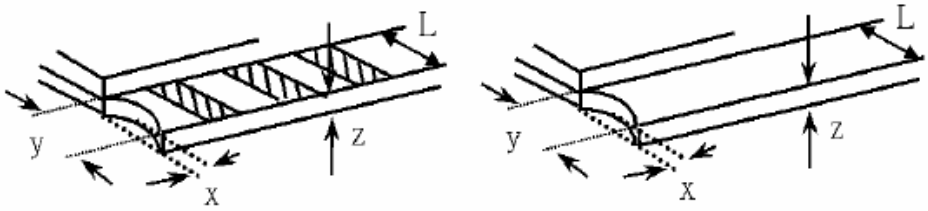
<table>
<tr><th>NO.</th><th>Item</th><th colspan="3">Criterion</th><th>AQL</th></tr>
<tr><td rowspan="6">04</td><td rowspan="6">Polarizer bubbles</td><td rowspan="6">If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction</td><td>Size Φ(mm)</td><td>Acceptable Q'ty</td><td rowspan="6">2.5</td></tr>
<tr><td>Φ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20< Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50< Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00< Φ</td><td>0</td></tr>
<tr><td>Total Q’ty</td><td>3</td></tr>
<tr><td>05</td><td>Scratches</td><td colspan="3">Follow NO.3 -2 Line Type.</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td colspan="3">Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.1 General glass chip:
6.1.1 Chip on panel surface and crack between panels:
 

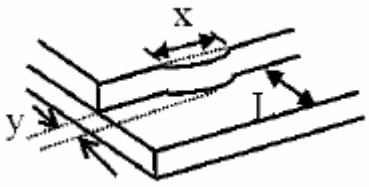
<table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr><tr><td>1/2t< z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip
6.1.2 Corner crack:
 

<table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr><tr><td>1/2t< z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip</td><td>2.5</td></tr>
</table>

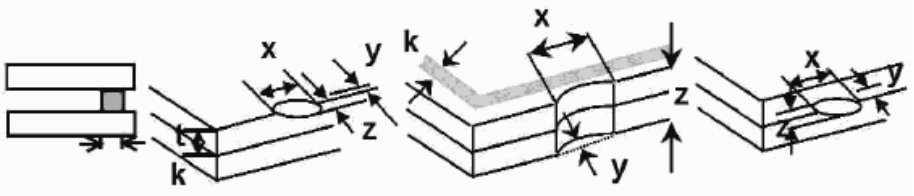
NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage ≦ 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage ≦ 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65

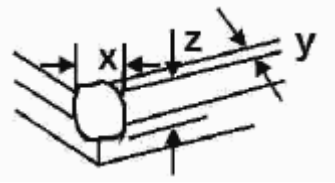
<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>07</td><td>Glass crack</td><td>
Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
7.2 Protrusion over terminal:
7.2.1 Chip on electrode pad:


<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0< z≦t</td></tr>
</table>
7.2.2
Non-conductive portion:


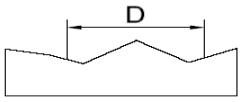
<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦L</td><td>x≦1/8a</td><td>0< z≦t</td></tr>
</table>
⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙ If the product will be heat sealed by the customer, the alignment mark must mot be damaged.
7.2.3 Substrate protuberance and internal crack


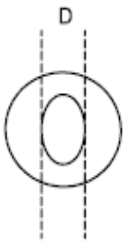
<table>
<tr><td>y: width</td><td>x: length</td></tr>
<tr><td>y≦1/3L</td><td>X≦a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>14</td><td>Touch Panel
Chipped
glass</td><td>Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Touch Panel Total thickness a: LCD side length
L: Electrode pad length
14.1 General glass chip:
14.1.1 Chip on panel surface and crack between panels:
 

<table>
<tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr>
<tr><td>Z≦t</td><td>≦1/2 k and not over viewing area</td><td>x≦1/8a</td></tr>
</table>
⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip
14.1.2 Corner crack:
 

<table>
<tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr>
<tr><td>z≦t</td><td>≦1/2 k and not over viewing area</td><td>x≦1/8a</td></tr>
</table>
⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>15</td><td>Touch Panel(Fish eye、dent and bubble on film)</td><td>
<table>
<tr><td>SIZE(mm)</td><td>Acceptable Q’ty</td></tr>
<tr><td>Φ≦0.2</td><td>Accept no dense</td></tr>
<tr><td>0.2< D ≦0.4</td><td>5</td></tr>
<tr><td>0.4< D ≦0.5</td><td>2</td></tr>
<tr><td>0.5< D</td><td>0</td></tr>
</table>




</td><td>2.5</td></tr>
<tr><td>16</td><td>Touch Panel Newton ring</td><td>Newton ring dimension ≦ 1/2 touch panel area and not affect font and line distortion(≦2.5%) , it is acceptable.</td><td>2.5</td></tr>
<tr><td>17</td><td>Touch Panel Linearity</td><td>Less than 2.5% is acceptable.</td><td>2.5</td></tr>
<tr><td>18</td><td>LCD Ripple</td><td>Touch the touch panel , can not see the LCD ripple.
Pen: R 1.0mm silicon rubber.
Operation Force: 80g</td><td>2.5</td></tr>
<tr><td>19</td><td>General appearance</td><td>19.1 Pin type must match type in specification sheet.
19.2 LCD pin loose or missing pins.
19.3 Product packaging must the same as specified on packaging specification sheet.
19.4 Product dimension and structure must conform to product specification sheet.</td><td>0.65
0.65
0.65
0.65</td></tr>
</table>

12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl) , Sulfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (Cl), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to POWER or GROUND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
  [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT , and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD